

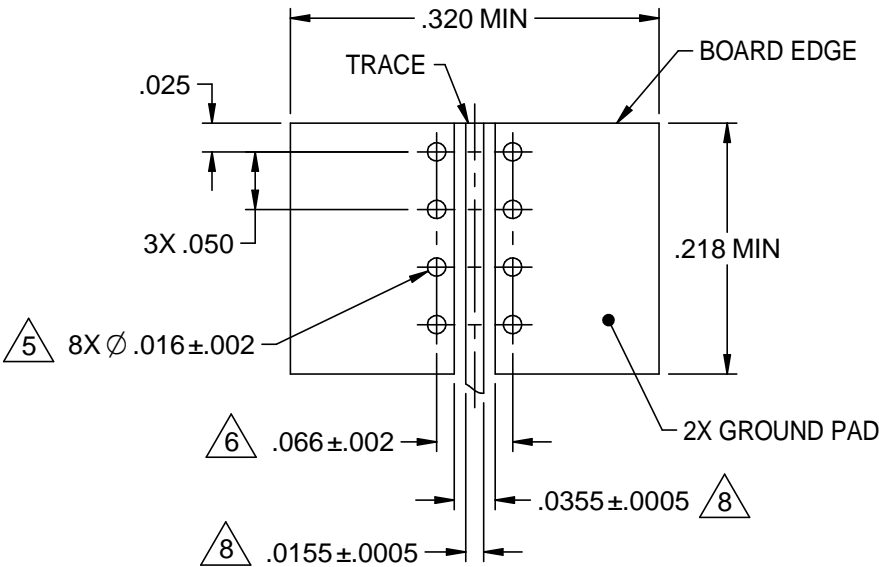
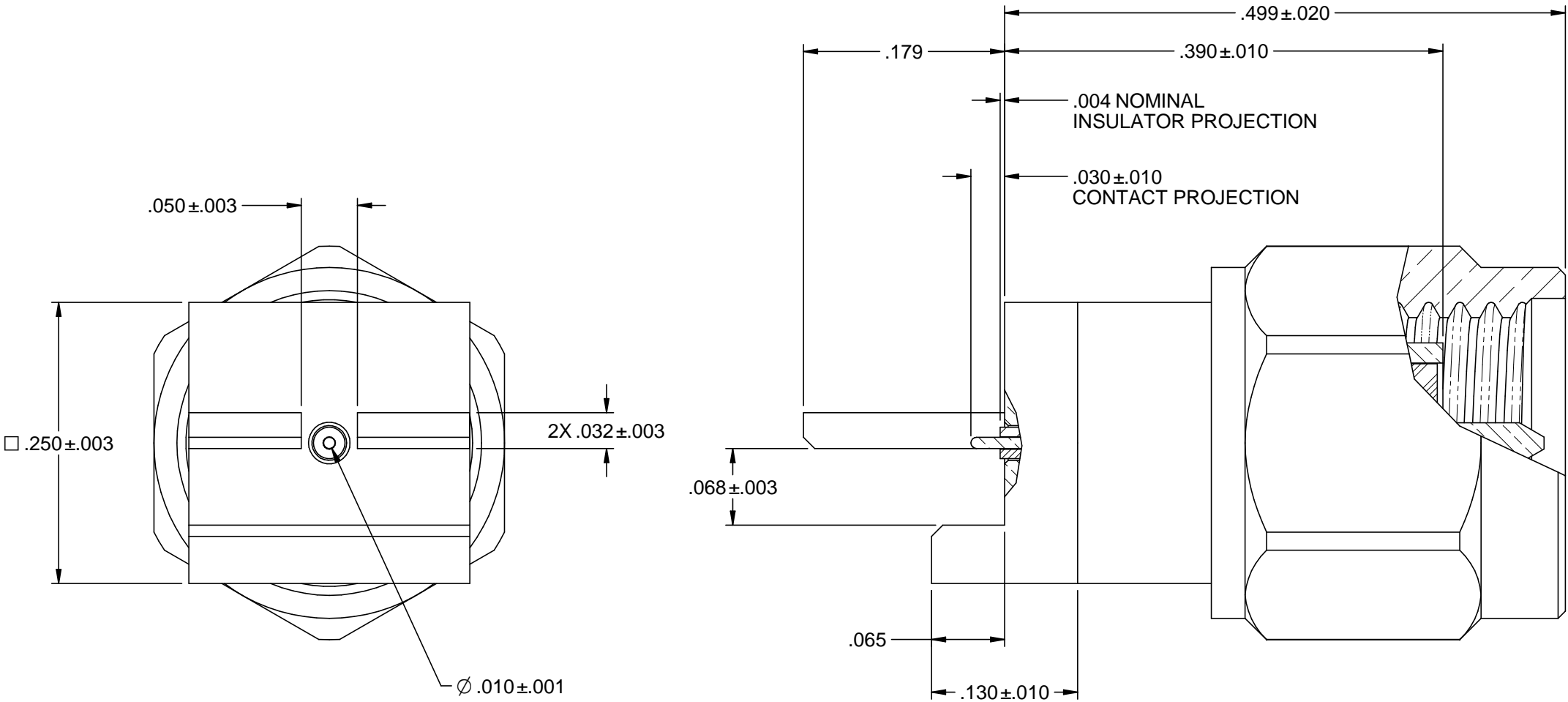
NOTES: UNLESS OTHERWISE SPECIFIED.

1. MATERIAL AND FINISH:  
1.1 BODY & COUPLING NUT: GOLD PLATED BRASS  
1.2 CONTACT: GOLD PLATED BERYLLIUM COPPER  
1.3 INSULATOR: PTFE (TEFLON)  
1.4 COUPLING SPRING: BERYLLIUM COPPER UNPLATED
2. ELECTRICAL SPECIFICATIONS:  
2.1 IMPEDANCE: 50 OHMS  
2.2 FREQUENCY: 0 - 26.5 GHz  
2.3 VSWR: 1.05+.02F(GHz) MAX AT 0-18 GHz, <1.50 TYPICAL AT 18-26.5 GHz  
2.4 WORKING VOLTAGE: 170 VRMS MAX AT SEA LEVEL  
2.5 DIELECTRIC WITHSTANDING VOLTAGE: 500 VRMS MIN AT SEA LEVEL  
2.6 INSULATION RESISTANCE: 1000 MEGOHMS MIN  
2.7 CONTACT RESISTANCE:  
    CENTER CONTACT: INTIAL 3.0 MILLIOHM MAX,  
                            AFTER ENVIRONMENTAL 4.0 MILLIOHM MAX  
    OUTER CONDUCTOR: INITIAL 2.0 MILLIOHM MAX,  
                            AFTER ENVIRONMENTAL - N/A  
2.8 CORONA LEVEL: 125 VOLTS MIN AT 70,000 FEET  
2.9 RF HIGH POTENTIAL WITHSTANDING VOLTAGE: 335 VRMS AT 4 & 7 MHz
3. MECHANICAL SPECIFICATIONS:  
3.1 ENGAGE/DISENGAGE TORQUE: 2 INCH-POUNDS MAX  
3.2 MATING TORQUE: 7-10 INCH-POUNDS WHEN BODY SUPPORTED WITH WRENCH  
                            8\* INCH POUNDS MAX UNSUPPORTED  
3.3 CONTACT RETENTION FORCE: 6 LBS MIN AXIAL FORCE ON MATING END  
  4 IN-OZ MIN RADIAL TORQUE  
3.4 DURABILITY: 500 CYCLES MIN
4. ENVIRONMENTAL:  
(MEETS OR EXCEEDS THE APPLICABLE PARAGRAPH OF MIL-PRF-39012)  
4.1 THERMAL SHOCK: MIL-STD-202, METHOD 107, CONDITION B,  
                            EXCEPT 115°C HIGH TEMP  
4.2 OPERATING TEMPERATURE: -65°C TO 165°C  
4.3 CORROSION: MIL-STD-202, METHOD 101, CONDITION B  
4.4 SHOCK: MIL-STD-202, METHOD 213, CONDITION I  
4.5 VIBRATION: MIL-STD-202, METHOD 204, CONDITION D  
4.6 MOISTURE RESISTANCE: MIL-STD-202, METHOD 106

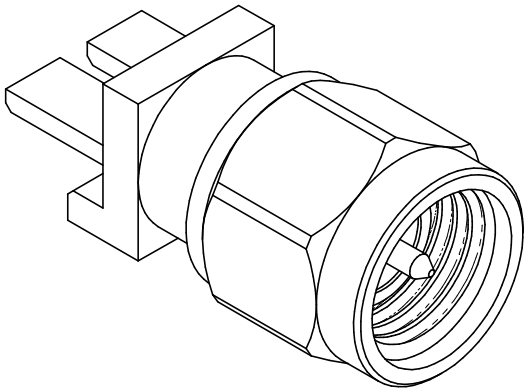
5. ALL HOLES PLATED THRU ENTIRE CIRCUIT BOARD STACKUP.
6. HOLE PATTERNS SYMMETRICAL ABOUT CENTER CPW TRACE.


7. FOR OPTIMUM CIRCUIT BOARD HIGH FREQUENCY PERFORMANCE:  
7.1 MAINTAIN SOLID GROUND PLANE BELOW HF SUBSTRATE.  
7.2 CONTROL PULLBACK OF TRACE AND GROUND FROM BOARD EDGE.  
7.3 CONTINUE GROUNDED COPLANAR LINE BEYOND GROUND PADS.  
7.4 PLACE 16 MIL DIA GROUND VIAS ON BOTH SIDE OF COPLANAR  
    WAVEGUIDE LINE AT 50 MIL INTERVALS ALONG ENTIRE LENGTH.  
7.5 IMMERSION GOLD PLATE (ENIG) ALL CONDUCTORS PER IPC-4552.

8. REFERENCE DIMENSIONS FOR 50 OHM GROUNDED CPW LINE, USING  
ROGERS R04003, 8 MIL HIGH FREQUENCY CIRCUIT BOARD SUBSTRATE:  
TRACE WIDTH: 15.5 MILS  
GROUND GAPS: 10 MILS  
CONDUCTOR THICKNESS: 1.4 MIL (INCLUDES PLATING)



MOUNTING FOOTPRINT  
(TOP VIEW, INCLUDING TRACE DIMENSIONS)



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	RoHS2 <input checked="" type="checkbox"/> 2011/65/EU		Title: PLUG ASSEMBLY, HIGH FREQ END LAUNCH, SMA, .010 MIL PIN		
	UNLESS OTHERWISE SPECIFIED UNITS: INCH		Model No. 142-0861-851		
	.XX ±.02 .XXX ±.005 ANGLES ±2°		Size B	DO NOT SCALE DRAWING	Date: 11/3/2014 Sheet 1 of 1